

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shailendra Mishra	03/20/2007
RECEIVING PARTY DATA	
Name:	Chartered Semiconductor Manufacturing Ltd.
Street Address:	60 Woodlands Industrial Park D
Internal Address:	Street 2
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	738406
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11683648
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	7649-24
NAME OF SUBMITTER:	Candi L. Riggs
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

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ASSIGNMENT

THIS ASSIGNMENT, made by me, **Shailendra Mishra**, a citizen of India, residing at 23 Van Horn Circle, Apt. C, Beacon, New York 12508, USA;

WHEREAS, I am a joint inventors of certain new and useful improvements in **METHODS OF FORMING MASK PATTERNS ON SEMICONDUCTOR WAFERS THAT COMPENSATE FOR NONUNIFORM CENTER-TO-EDGE ETCH RATES DURING PHOTOLITHOGRAPHIC PROCESSING**, for which an application was filed on **March 8, 2007** and assigned U.S. Application Serial No. **11/683,648**; and

WHEREAS, **Chartered Semiconductor Manufacturing Ltd.**, a Singapore corporation having a principal place of business at 60 Woodlands Industrial Park D, Street 2, Singapore 738406; hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by these presents do hereby sell, assign, transfer, and convey unto the said assignee, its successors and assigns, the entire right, title, and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues or other forms of protection thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted along with any term extensions thereon or therefor, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

I hereby request that said Letters Patent be issued in accordance with this assignment.

ASSIGNMENT - CONTINUED

I further covenant and agree that, at the time of the execution and delivery of these presents, I possess full title to the invention and application above-mentioned, and that I have the unencumbered right and authority to make this assignment.

I further covenant and agree to promptly communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors, or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns, and other legal representatives; and I hereby instruct, and further covenant and agree to bind our heirs, legal representatives, and assigns, to do same, without further compensation, but at the expense of said assignee or its representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 20 day of March, 2007.



Shailendra Mishra (SEAL)

Witnessed by:

Date: _____